

ELECTRONIC SUBSTRATE HOUSING EQUIPMENT AND ELECTRIC APPARATUS

ABSTRACT

An electronic substrate 200A mounts a heater element 220. A chassis 300A houses an electronic substrate 200 in an airtight manner. A cooling unit 400 cools the electronic substrate 200. The cooling unit 400 includes a heat receiving part 410 and a heat radiation part 420. The heat receiving part 410 receives heat from the electronic substrate 200. The heat radiation part 420 is connected with the heat receiving part 410, and radiates heat from the electronic substrate 200 which has received by the heat receiving part 410. Further, the heat receiving part 410 is provided in the chassis 300A in an airtight manner, and the heat radiation part 420 is provided outside the chassis 300. As a result, efficient cooling is possible, and moreover, maintenance replacement work can be performed for each piece of electronic substrate housing equipment individually.

Figure 1